



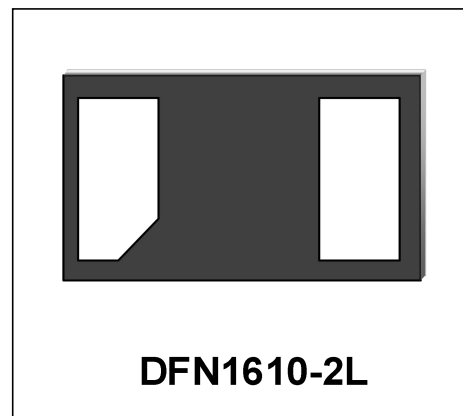
ETEK
Microelectronics

ES45DPX

Transient Voltage Suppressor

Features

- Small Body Outline Dimensions:
0.063" x 0.040" (1.6 mm x 1.0 mm)
- Protects one I/O or power line
- Low Clamping Voltage
- Working Voltage: 4.85V
- Low Leakage Current
- Response Time is Typically < 1 ns



IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30\text{kV}$ (air), $\pm 30\text{kV}$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 170A (8/20 μs)

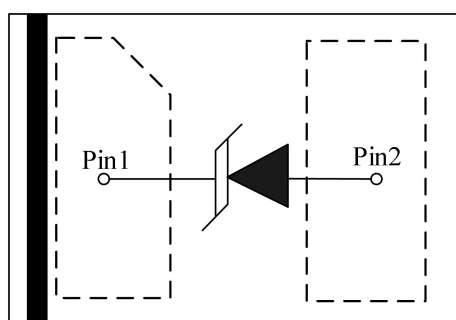
Mechanical Characteristics

- DFN1610-2L package
- Molding compound flammability rating:
UL 94V-0
- Marking: Marking Code
- Packaging: Tape and Reel per EIA 481
- RoHS Compliant
- MSL1

Applications

- Laptop Computers
- Cellular Phones
- Digital Cameras
- Personal Digital Assistants (PDAs)

Schematic & PIN Configuration



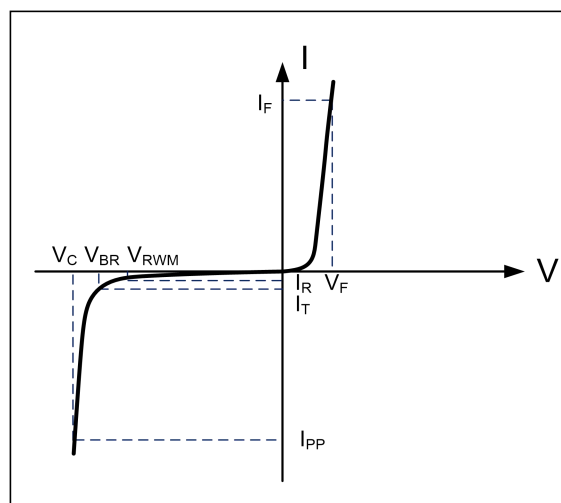
(TOP VIEW)

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p=8/20\mu s$)	P_{PP}	2550	Watts
Peak Pulse Current ($t_p=8/20\mu s$)	I_{PP}	170	A
Operating Temperature	T_J	-55 to + 125	$^{\circ}C$
Storage Temperature	T_{STG}	-55 to +150	$^{\circ}C$

Absolute Maximum Rating

Electrical Parameters (T=25 $^{\circ}C$)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



Electrical Characteristics

ES45DPX						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				4.85	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	5.0		6.5	V
Forward Voltage	V_F	$I_F=10mA$	0.6		1.0	V
Reverse Leakage Current	I_R	$V_{RWM}=4.85V, T=25^{\circ}C$			500	nA
Clamping Voltage	V_C	$I_{PP}=170A, t_p=8/20\mu s$		13	15	V
Dynamic Resistance ^{1,2}	R_{DYN}	$TLP=0.2/100ns$		0.05		Ω
Junction Capacitance	C_j	$V_R=0V, f=1MHz$		500	700	pF

Notes: 1、TLP Setting: $t_p=100ns$, $t_r=0.2ns$, I_{TLP} and V_{TLP} sample window: $t_1=70ns$ to $t_2=90ns$.

2、Dynamic resistance calculated from $I_{PP}=4A$ to $I_{PP}=16A$ using “Best Fit” .

Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

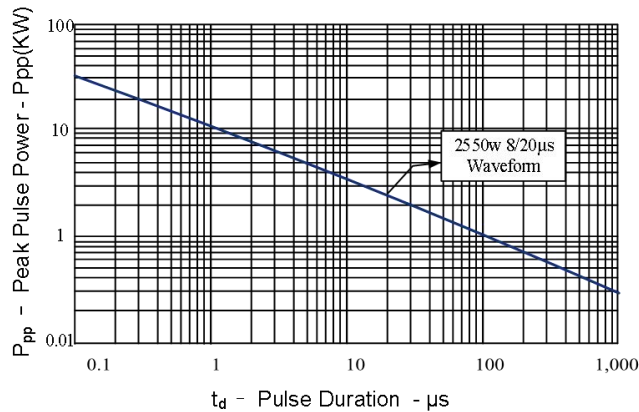


Figure 2: Power Derating Curve

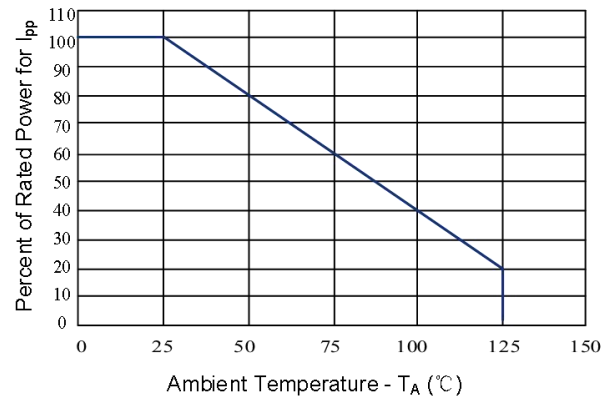


Figure 3: Clamping Voltage vs. Peak Pulse Current

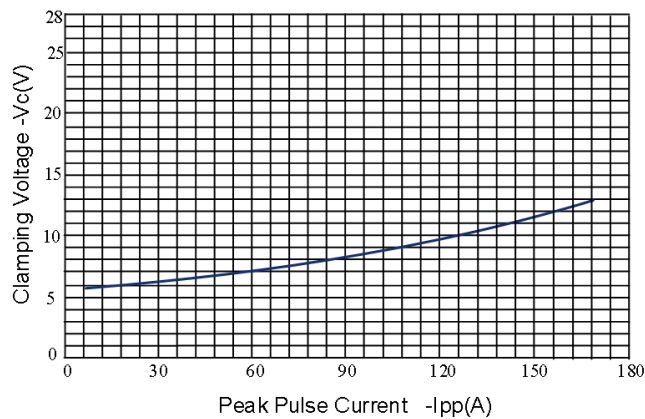


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

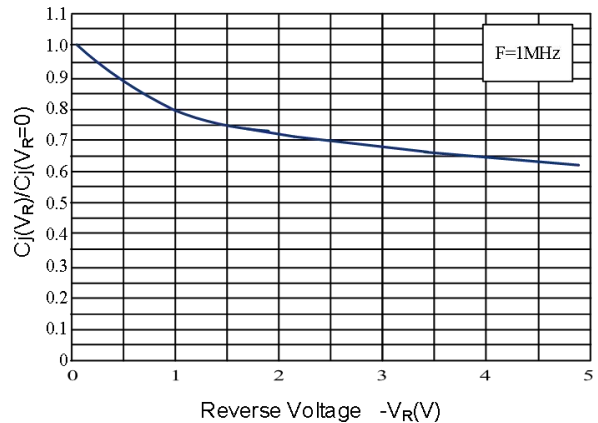


Figure 5: Pulse Waveform

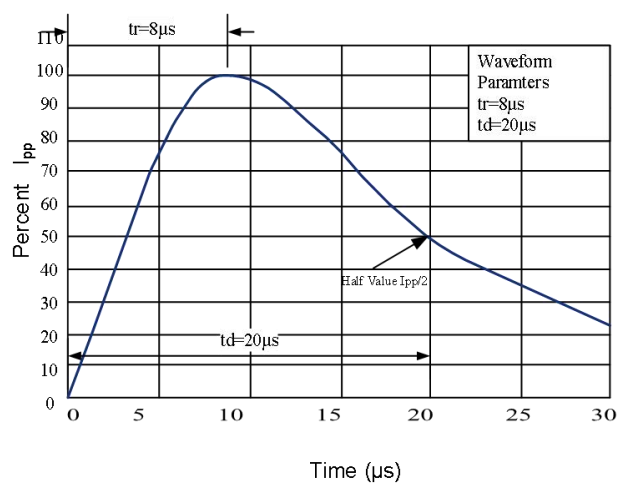
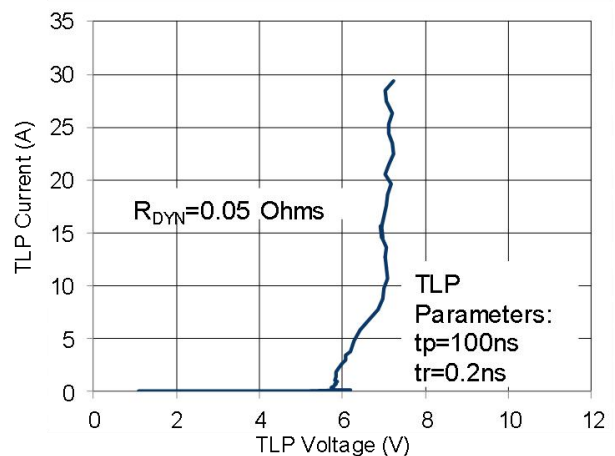
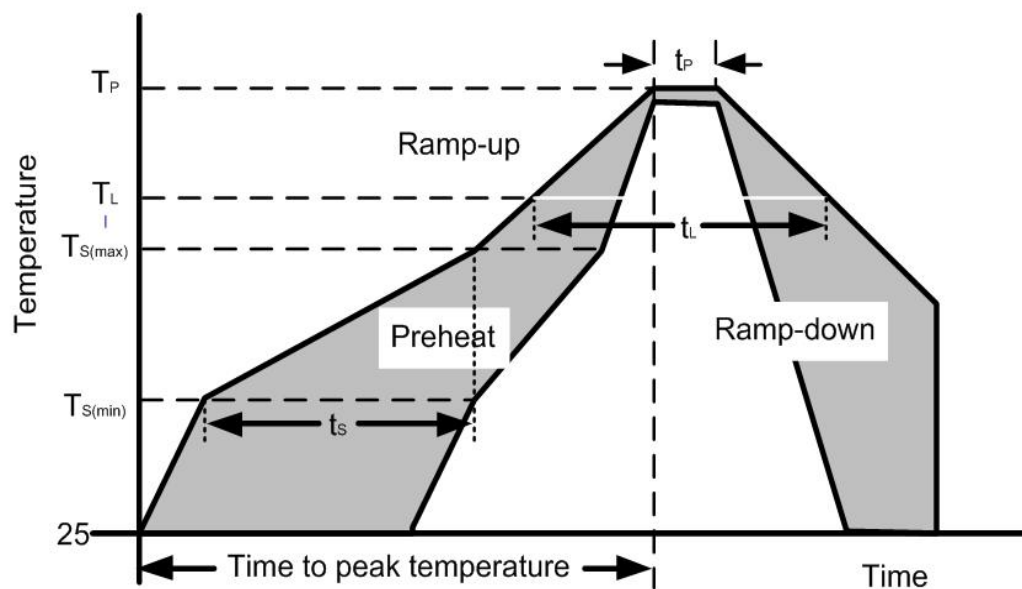


Figure 6: TLP Curve

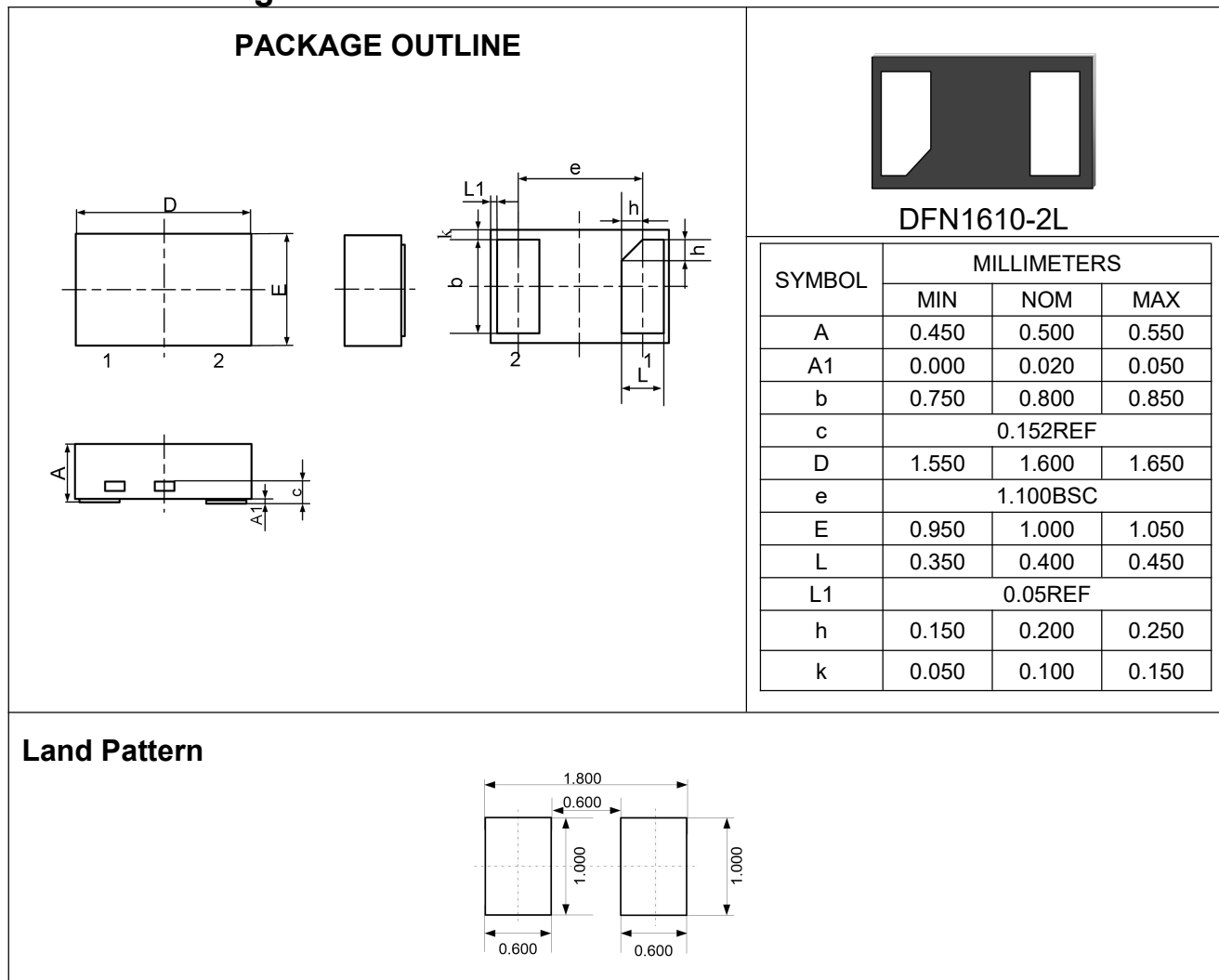


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{s(max)}$ to T_L ——Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



Outline Drawing –DFN1610-2L



Marking Codes

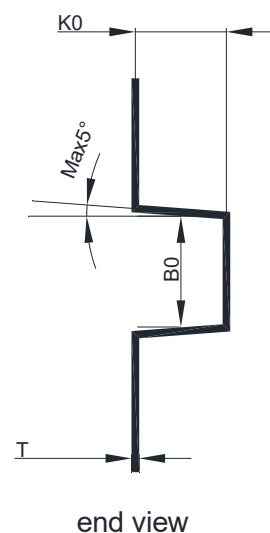
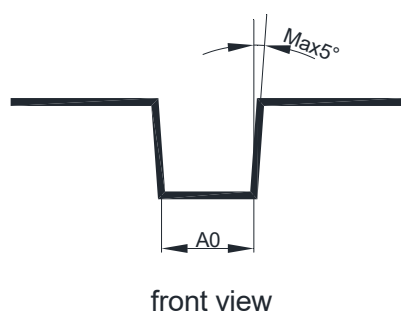
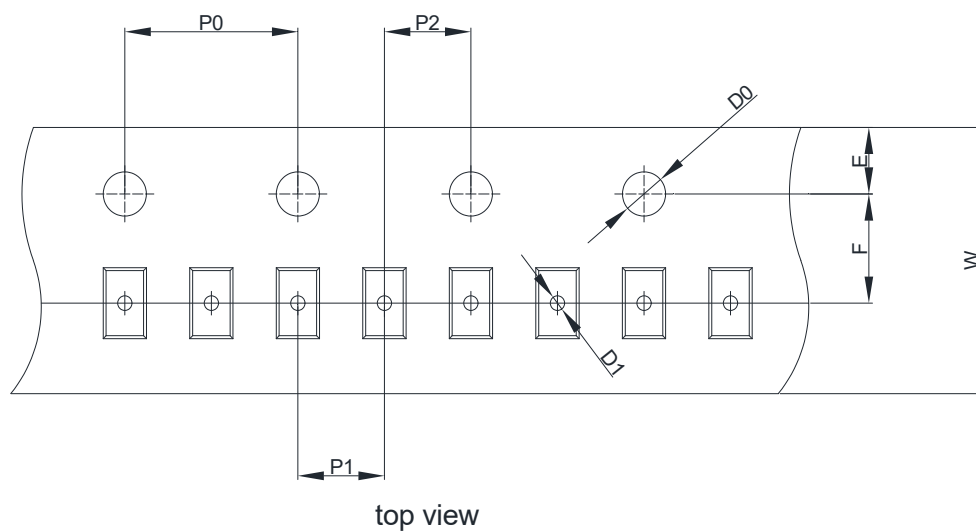
Part Number	Marking Code
ES45DPX	Pin1 MX Pin2 M=Specific Device Code X=Tracking Number

Package Information

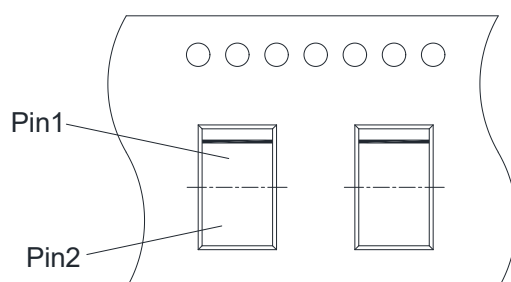
Qty: 10k/Reel

Tape Information

Tape Dimensions



Quadrant Assignments For PIN1 Orientation In Tape



User Direction of Feed

SYMBOL	A0	B0	K0	P0	P1	P2
SPEC	1.15±0.05	1.78±0.05	0.63±0.05	4.00±0.10	2.00±0.05	2.00±0.05
SYMBOL	T	E	F	D0	D1	W
SPEC	0.20±0.02	1.75±0.10	3.50±0.05	1.50 ^{+0.1} ₀	0.50 ^{+0.05} ₀	8.00 ^{0.3} _{±0.1}

Revision History

No.	Version	Date	Revision Item	Request	Function and characteristic checking	Package dimension checking	Typos checking
1	1.0	2018-09-28	Released Version 2019.01.03 Double check	Qi Shu Kun	Yin Peng	Ge Zheng Bing	Liu Jia Ying
2	1.1	2019-02-25	1.Change the V_{RWM} from 4.5V to 4.85V 2.Change the Min value of V_{BR} from 4.8V to 5V.	Qi Shu Kun	Yin Peng	Ge Zheng Bing	Liu Jia Ying
3	1.2	2019-08-20	Add tape information	Qi Shu Kun	Yin Peng	Ge Zheng Bing	Liu Jia Ying
4	1.3	2020-03-17	Add MSL level	Qi Shu Kun	Qi Shu Kun	Liu Jia Ying	Liu Jia Ying
5	1.4	2020-07-07	Update tape information	Qi Shu Kun	Qi Shu Kun	Liu Jia Ying	Liu Jia Ying
6	1.5	2020-11-10	Update Marking Information	Qi Shu Kun	Qi Shu Kun	Liu Jia Ying	Liu Jia Ying
7	1.6	2022-02-17	Update Tape Information	Qi Shu Kun	Qi Shu Kun	Liu Jia Ying	Liu Jia Ying